ELECTRONIC PACKAGING (Z112)

Graduate Certificate Program
College: Engineering

Abstract
The Graduate Certificate in Engineering program is designed to assist engineers and technical professionals in the development of their careers and to provide the expertise needed in the rapidly changing business, government, and industrial environments.

Our electronic packaging Graduate Certificate in Engineering leverages the university’s unique strength in reliability along with its expertise in electrical engineering, mechanical engineering, materials science, and business to empower students to further careers in areas such as avionics, automotive electronics, industrial motor drives, military electronics, and medical equipment. Course topics include basics of electronic system integration, heat transfer, thermal management, stress analysis, cost analysis, quality and reliability assessment, and prognostics and health management.

Financial Assistance
Students in this program pay a special tuition rate, which does not differ between residents and non-residents of Maryland. This rate is not fully covered by graduate assistantships, fellowships or the tuition remission. Additional graduate student fees are charged. Tuition and fees are subject to change.

This program does not provide departmental assistantships or fellowships. Loans, work-study and need-based grants for citizens and permanent residents with demonstrated financial need may submit a Free Application for Federal Student Aid (FAFSA) by appropriate FAFSA deadlines. For more information on this process, visit: https://fafsa.ed.gov/deadlines.htm.

Contact
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Courses: ENRE (https://umd-curr.courseleaf.com/graduate/courses/enre/) ENME (https://umd-curr.courseleaf.com/graduate/courses/enme/)

Admissions
General Requirements
• Statement of Purpose (https://advancedengineering.umd.edu/application-process/)
• Transcript(s)
• TOEFL/IELTS/PTE (international graduate students (https://gradschool.umd.edu/admissions/english-language-proficiency-requirements/))

Program-Specific Requirements
• Two (2) Letters of Recommendation are required for anyone with an undergraduate GPA below 3.0. Anyone with a GPA 3.0 or above should contact the Office of Advanced Engineering Education with a request to waive this requirement.

For additional program-specific admission requirements, please visit: https://advancedengineering.umd.edu/electronic-packaging (https://advancedengineering.umd.edu/electronic-packaging/)

*Visa Eligibility: This program is not eligible for i-20 or DS-2019 issuance by the University of Maryland. For anyone needing these documents, consider applying for a full-time master’s program offered on campus (https://gradschool.umd.edu/engineering/meng-campus/).

Applicants with an undergraduate GPA of less than 3.0 may be admitted on a provisional basis if they have demonstrated satisfactory performance in another graduate program and/or their work has been salutary.

Applicants with foreign credentials must submit academic records in the original language with literal English translations. Allow at least three months for evaluation of foreign credentials. International applicants are advised to review the Graduate School English requirements to learn whether or not the submission of TOEFL or IELTS scores is required. For more information on the Office of Advanced Engineering Education admissions process: https://advancedengineering.umd.edu/application-process (https://advancedengineering.umd.edu/application-process/).

For more admissions information or to apply to the program, please visit our Graduate School website: www.gradschool.umd.edu/admissions (http://www.gradschool.umd.edu/admissions/)

Application Deadlines

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<thead>
<tr>
<th>Type of Applicant</th>
<th>Fall Deadline</th>
<th>Spring Deadline</th>
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<tbody>
<tr>
<td>Domestic Applicants</td>
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<tr>
<td>US Citizens and Permanent Residents</td>
<td>Fall 2019: 26 July</td>
<td>13 Dec</td>
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<td>Fall 2020: 31 July</td>
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<tr>
<td>International Applicants</td>
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<tr>
<td>F (student) or J (exchange visitor) visas; A,E,G,H,I and L visas and immigrants</td>
<td>This certificate is not currently accepting applications</td>
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Other Deadlines: Please visit the program website at http://www.advancedengineering.umd.edu

Requirements
• Electronic Packaging, Post-Baccalaureate Certificate (P.B.C.) (https://academiccatalog.umd.edu/graduate/programs/electronic-packaging-z112/electronic-packaging-pbc/)

Facilities and Special Resources
This program is currently offered in-person at the College Park Campus. In addition to in-person courses, you may have the option to take some
course requirements in an online format. Course format offerings are subject to change.

This program is also offered 100% online. Please see Electronic Packaging (Z111) for more information.